

Removal of iLGA Converters DCAN-62

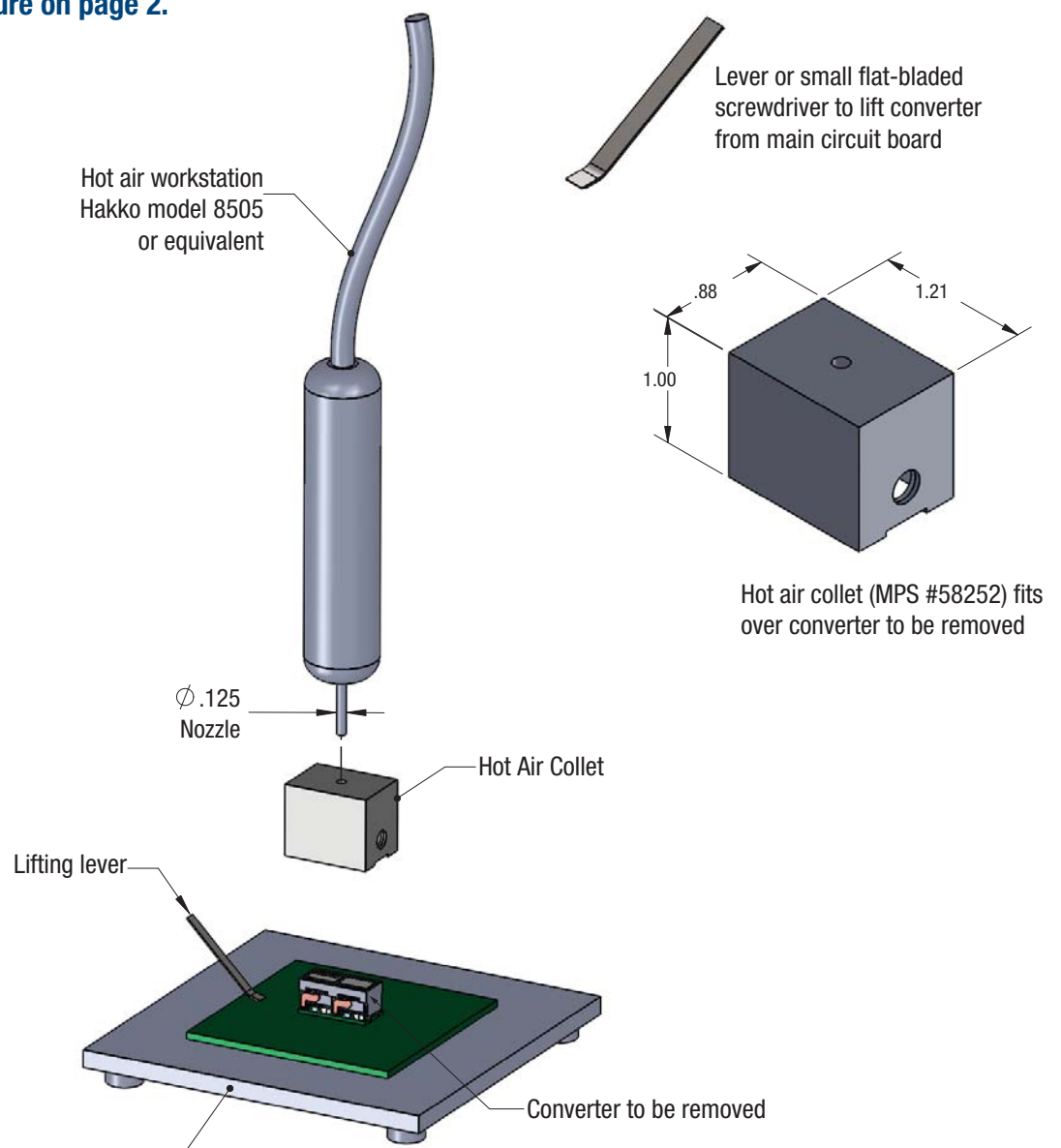
iLGA Device Removal

The following procedure is a generic guideline to remove iLGA converters from a circuit board assembly. Note that the removed device will not be salvageable and cannot always be analyzed to determine mode of failure. Parts on the subject converter may be displaced during this rework.

Tools Required

1. Hot Plate capable of pre-heating the main circuit board to 250°C (Optional but recommended for best result)
2. Forced Hot Air rework station (Hakko Model 8505 or equivalent with $\varnothing.125$ nozzle)
3. Lifting lever or small flat-bladed screwdriver to lift the converter away from the main circuit board once the solder has reached liquidus state

Please see Removal Procedure on page 2.



Whenever feasible, pre-heat main board on hot plate to approximately 250°C.
This reduces the stress caused from heating the subject assy strictly from the top.

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Removal Procedure

1. If using hot plate, place main PCB on plate and heat to approximately 250°C.
2. Position collet over device to be removed.
3. With workstation heat temp set at level 7 (out of 8) and air flow set to 6 (out of 8), insert $\varnothing.125$ tip in hole at top of collet.
4. Apply heat for two minutes (three minutes without hot plate) keeping collet tight against main board surface
5. Without disengaging workstation nozzle, use lifting lever placed under the edge of the board to be removed. If board is still firmly attached, continue to apply heat until the solder liquefies and board can be easily lifted away.

Prepare for Replacement

Carefully remove residual solder and debris from the pads using flux-coated braid and flat-tipped soldering iron or other appropriate technique. Great care must be used to prevent lifting of small pads. Clean the entire area of flux and debris.

Converter Replacement

It is suggested that solder paste be applied to the new converter. A mini solder paste stencil will ensure the proper paste thickness based on the existing reflow process but a manual application of paste is also feasible. Carefully position the pasted converter and reflow the entire assembly using standard reflow profile. No study has been performed to reliably predict the acceptability of solder joints created using this technique.

Inspect

After cool-down period, visually inspect the castellated hole around the perimeter of the new converter where applicable. When the unit is properly soldered, the solder should partially wick up into these castellations.